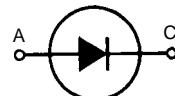


# Fast Recovery Epitaxial Diode (FRED)

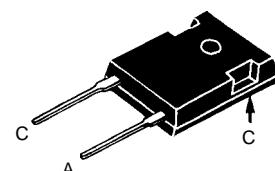
**DSEI 30**

**I<sub>FAVM</sub> = 30 A**  
**V<sub>RRM</sub> = 1000 V**  
**t<sub>rr</sub> = 35 ns**

V <sub>RSM</sub>	V <sub>RRM</sub>	Type
V	V	
1000	1000	DSEI 30-10A



TO-247 AD



A = Anode, C = Cathode

Symbol	Test Conditions	Maximum Ratings	
I <sub>FRMS</sub>	T <sub>VJ</sub> = T <sub>VJM</sub>	70	A
I <sub>FAVM</sub> *	T <sub>C</sub> = 85°C; rectangular, d = 0.5	30	A
I <sub>FRM</sub>	t <sub>p</sub> < 10 µs; rep. rating, pulse width limited by T <sub>VJM</sub>	375	A
I <sub>FSM</sub>	T <sub>VJ</sub> = 45°C; t = 10 ms (50 Hz), sine	200	A
	t = 8.3 ms (60 Hz), sine	210	A
	T <sub>VJ</sub> = 150°C; t = 10 ms (50 Hz), sine	185	A
	t = 8.3 ms (60 Hz), sine	195	A
J <sub>i²dt</sub>	T <sub>VJ</sub> = 45°C t = 10 ms (50 Hz), sine	200	A²s
	t = 8.3 ms (60 Hz), sine	180	A²s
	T <sub>VJ</sub> = 150°C; t = 10 ms (50 Hz), sine	170	A²s
	t = 8.3 ms (60 Hz), sine	160	A²s
T <sub>VJ</sub>		-40...+150	°C
T <sub>VJM</sub>		150	°C
T <sub>stg</sub>		-40...+150	°C
P <sub>tot</sub>	T <sub>C</sub> = 25°C	138	W
M <sub>d</sub>	Mounting torque with screw M3	0.45/4	Nm/lb.in.
	Mounting torque with screw M3.5	0.55/5	Nm/lb.in.
Weight		6	g

Symbol	Test Conditions	Characteristic Values	
		typ.	max.
I <sub>R</sub>	T <sub>VJ</sub> = 25°C V <sub>R</sub> = V <sub>RRM</sub>	750	µA
	T <sub>VJ</sub> = 25°C V <sub>R</sub> = 0.8 • V <sub>RRM</sub>	250	µA
	T <sub>VJ</sub> = 125°C V <sub>R</sub> = 0.8 • V <sub>RRM</sub>	7	mA
V <sub>F</sub>	I <sub>F</sub> = 30 A; T <sub>VJ</sub> = 150°C	2	V
	T <sub>VJ</sub> = 25°C	2.4	V
V <sub>To</sub>	For power-loss calculations only	1.5	V
r <sub>T</sub>	T <sub>VJ</sub> = T <sub>VJM</sub>	12.5	mΩ
R <sub>thJC</sub>		0.9	K/W
R <sub>thCK</sub>		2.5	K/W
R <sub>thJA</sub>		35	K/W
t <sub>rr</sub>	I <sub>F</sub> = 1 A; -di/dt = 100 A/µs; V <sub>R</sub> = 30 V; T <sub>VJ</sub> = 25°C	35	ns
I <sub>RM</sub>	V <sub>R</sub> = 540 V; I <sub>F</sub> = 30 A; -di <sub>F</sub> /dt = 240 A/µs L ≤ 0.05 µH; T <sub>VJ</sub> = 100°C	16	18 A

\* I<sub>FAVM</sub> rating includes reverse blocking losses at T<sub>VJM</sub>, V<sub>R</sub> = 0.8 V<sub>RRM</sub>, duty cycle d = 0.5  
Data according to DIN/IEC 747

IXYS reserves the right to change limits, test conditions and dimensions

## Features

- International standard package JEDEC TO-247 AD
- Planar passivated chips
- Very short recovery time
- Extremely low switching losses
- Low I<sub>RM</sub>-values
- Soft recovery behaviour
- Epoxy meet UL 94V-0

## Applications

- Antiparallel diode for high frequency switching devices
- Anti saturation diode
- Snubber diode
- Free wheeling diode in converters and motor control circuits
- Rectifiers in switch mode power supplies (SMPS)
- Inductive heating and melting
- Uninterruptible power supplies (UPS)
- Ultrasonic cleaners and welders

## Advantages

- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses
- Operating at lower temperature or space saving by reduced cooling

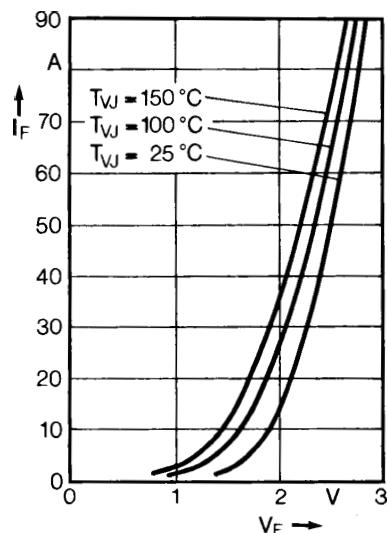


Fig. 1 Forward current versus voltage drop.

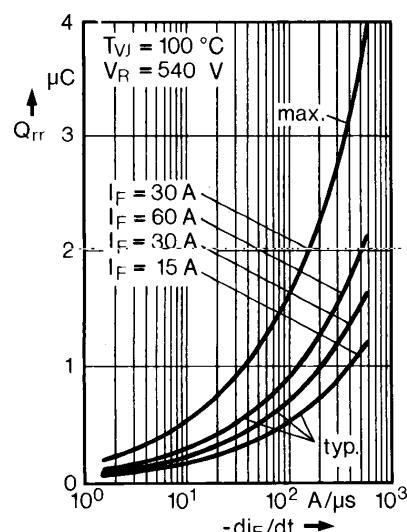


Fig. 2 Recovery charge versus  $-di_F/dt$ .

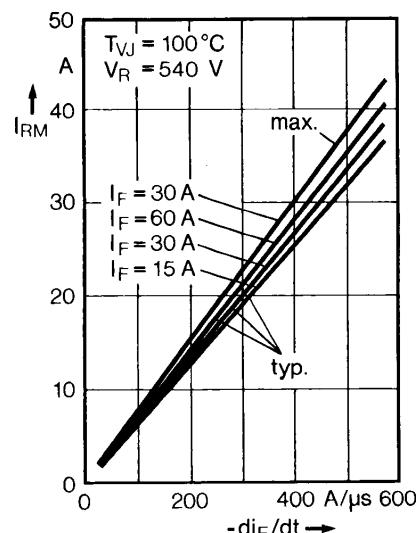


Fig. 3 Peak reverse current versus  $-di_F/dt$ .

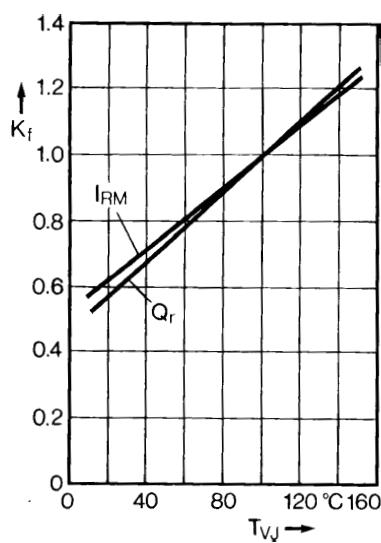


Fig. 4 Dynamic parameters versus junction temperature.

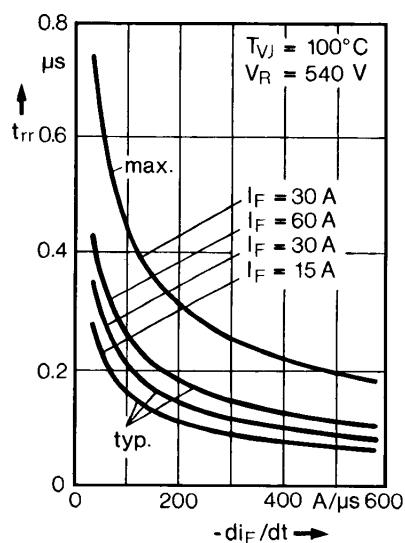


Fig. 5 Recovery time versus  $-di_F/dt$ .

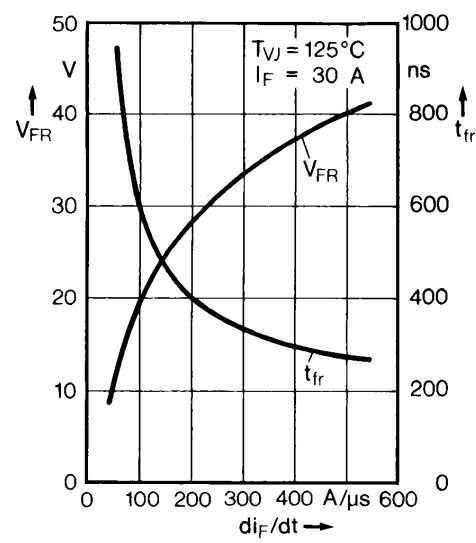


Fig. 6 Peak forward voltage versus  $di_F/dt$ .

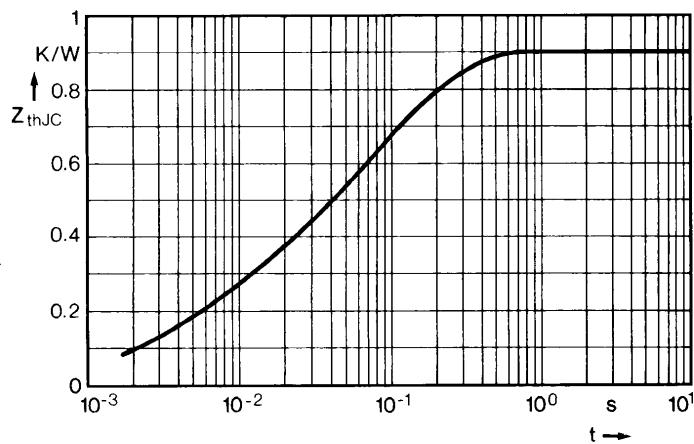
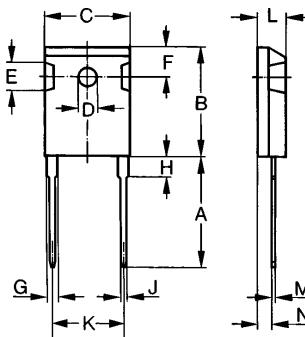


Fig. 7 Transient thermal impedance junction to case.

### Dimensions



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102